

electronic component is mounted on the board by the electronic component mounting method claimed in any one of claims 1 through 9, 14 through 17, 25 through 32, 36 through 40 and 43.

- 5 45. An electronic component mounting apparatus as claimed in claim 11 or 34, wherein the apparatus for metallically bonding the gold bump to the electrode of the board with supersonic waves applied comprises a heating member for effecting heating from the upper surface side of
- 10 the electronic component or from the board side or from both the electronic component side and the board side, and the heating is effected by the heating member at a time of metallic bonding.

## ABSTRACT

A chip is bonded on a circuit board by aligning in position bumps 3 with board electrodes 5 with interposition of an anisotropic conductive layer 10 in which an insulating resin is mixed with conductive particles 10a and an inorganic filler 6f, and pressing the chip 1 against the board 4 with a pressure force of not smaller than 20 gf per bump applied to the chip 1 against the board 4 by means of a head 8 while correcting warp of the chip and the board and crushing the bumps, and hardening the insulating resin.

Fig. 1A

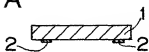


Fig. 1C



Fig. 1B

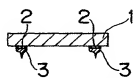


Fig. 1D

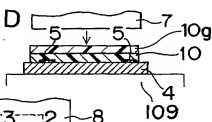


Fig. 1E

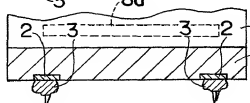


Fig. 1F

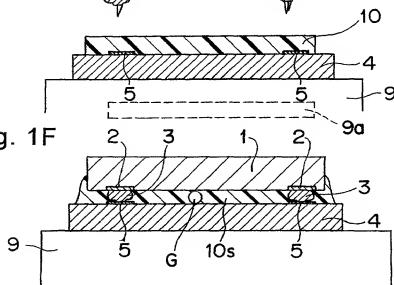


Fig. 1G

